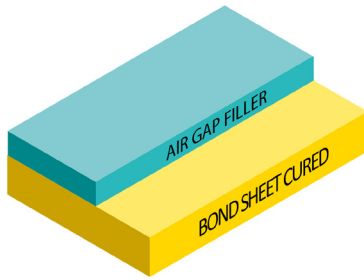


BOND SHEET CURED HTG + AIR GAP FILLER

Data Sheet DS_66

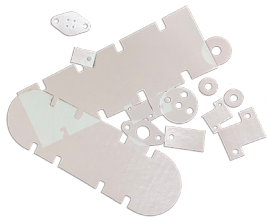
1/2

STANDARD CONSTRUCTION



Air gap filler μm (mils)
50 / (1,9), 70 / (2,7)

Bonsheet cured μm (mils)
80 / (3.1)



UL Approved QMST2
File: E47820
IPC-4101



RoHS 3 / REACH
Last updated compliance directive



DESCRIPTION

- Ultra-thin dielectric layer, high dielectric strength, high thermal conductivity and low thermal resistance.
- Consisting of a glass fabric base, enriched with mineral fillers.
- Thermal conductivity BSC 3.2 W/mK with dielectric strengths greater than 4 KV (80 μm dielectric) .
- Low thermal resistance, which efficiently dissipates the heat generated by the power components to the cooling elements.
- Silicon free.
- Ideal for pick and place automation
- One or two sides with Aismalibar Thermal air gap filler, a unique technology that provides air gap filling capacity when TIM arrives to 35-40°C
- Low mounting pressure
- No need of thermal grease
- Offered in cut two size
- Dry surface , non-tacky
- No need to peel a liner
- ideal for pick and place automation
- Very low CTE expansion

Properties	BSC80 HTG 1GF50	UNITS	TOLERANCE	TEST METHOD
Thermal conductivity	3 (0,076)*	W/mK (W/inK)	+/- 15%	ASTM D5470
Thermal Resistance	0,051	K/W	+/- 15%	ASTM D5470
Thermal impedance @10/30/50 psi	0,433	Kcm ² /W	+/- 15%	ASTM D5470
Nominal thickness (pressed)	130 (5,1)	μm (mils)	+/- 15 μm (0,6mils)	-
Reinforcement Carrier on BSC HTg	Glass fiber			-
Flammability / Flame Rating	V-0**	class	-	UL-94
Dielectric breakdown voltage, AC	≥ 4	kV	-	IPC TM 650 2.5.6.3
Weight Loss	< 0,5	%		ASTM E595
Density	2,6	g/cm ³	+/- 10%	ASTM D792
Area weight	195	g/m ²	+/- 20g/m ²	-
Continuous Working Temperature	130*	°C	-	UL-MOT
Volume Resistivity (los tenemos H Tg)	1.82E+14*	Ohm-cm	-	ASTM D257
Surface Resistivity (los tenemos H Tg)	2.14E+13*	Ohm		ASTM D257
Decomposition Temperature (Td) Initial	340*	°C	-	IPC-TM 650-2.3.41
Decomposition Temperature (Td) 5% loss	420*	°C	-	IPC-TM 650-2.3.41
Glass transition temperature of dielectric layer (by DSC)	180*	°C	-	IPC-TM 650-2.4.24
Permittivity	6,7 (0,170) *	pF/m (pF/in)	-	
CTE (x,y)	14-15*	ppm/°C	-	IPC-TM 650-2.4.41
CTE (z) <Tg	37*	ppm/°C	-	IPC-TM 650-2.4.24
CTE (z) >Tg	172*	ppm/°C	-	IPC-TM 650-2.4.24
Z-axis Expansion (50-250°C)	1.8 (77ppm)*	%	-	IPC-TM 650-2.4.24

STORAGE CONDITIONS

Keep storage climate conditions below 24°C and 55% relative humidity. In the event of storing under very low warehouse temperatures give some time for the packed TIM's to stabilize to room temperature before opening. Keeping the above mentioned storage conditions and avoiding TIM's damage by humidity uptake will give a useful life of 6 months after production date.

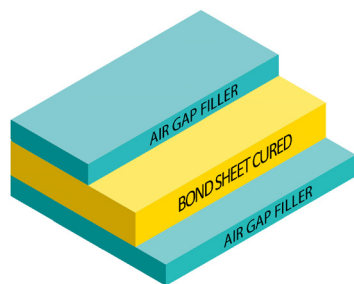
(*) Value only of the Bond Sheet Cured.

(**)Flammability rating is only valid when BSC70/100 or BSC80 HTG with one or two sides GF50 is clad to an aluminium laminate of 0,8mm or higher and at the other side an FR4 with V-0 recognition with 0,8mm or higher.

BOND SHEET CURED HTG + 2 AIR GAP FILLER

Data Sheet DS_66 2/2

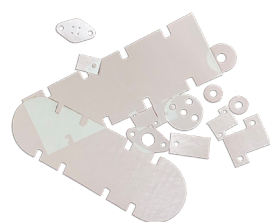
STANDARD CONSTRUCTION



Air gap filler μm (mils)
50 / (1,9), 70 / (2,7)

Bonsheet cured μm (mils)
80/(3.1)

Air gap filler μm (mils)
50 / (1,9), 70 / (2,7)



UL Approved QMST2
File: E47820
IPC-4101



RoHS 3 / REACH
Last updated compliance directive



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Properties	BSC80 HTG 2GF50	UNITS	TOLERANCE	TEST METHOD
Thermal conductivity	3 (0,076)*	W/mK (W/inK)	+/- 15%	ASTM D5470
Thermal Resistance	0,070	K/W	+/- 15%	ASTM D5470
Thermal impedance @10/30/50 psi	0,600	Kcm ² /W	+/- 15%	ASTM D5470
Nominal thickness (pressed)	180 (7,1)	μm (mils)	+/- 15 μm (0,6mils)	-
Reinforcement Carrier on BSC HTg	Glass fiber			-
Flammability / Flame Rating	V-0**	class	-	UL-94
Dielectric breakdown voltage, AC	≥ 4	kV	-	IPC TM 650 2.5.6.3
Weight Loss	< 0,5	%		ASTM E595
Density	2,6	g/cm ³	+/- 10%	ASTM D792
Area weight	195	g/m ²	+/- 20g/m ²	-
Continuous Working Temperature	130*	°C	-	UL-MOT
Volume Resistivity (los tenemos H Tg)	1.82E+14*	Ohm-cm	-	ASTM D257
Surface Resistivity (los tenemos H Tg)	2.14E+13*	Ohm		ASTM D257
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Glass transition temperature of dielectric layer (by DSC)	180*	°C	-	IPC-TM 650-2.4.24
Permittivity	6,7 (0,170) *	pF/m (pF/in)	-	
CTE (x,y)	14-15*	ppm/°C	-	IPC-TM 650-2.4.41
CTE (z) <Tg	37*	ppm/°C	-	IPC-TM 650-2.4.24
CTE (z) >Tg	172*	ppm/°C	-	IPC-TM 650-2.4.24
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